


## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	Improved Cobalt Silicidation Process for Substrates with a Silicon Germanium Layer		
Application Type : regular, utility Attorney Docket Number : 2001.1531/24061.439			
Correspondence address: Customer Number: 42717 			
Priority Data: Doc.No: 92116010; Country -TW ; Date: 2003-06-12 us-priority-claimed			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Publication Information:

Suggested Figure for Publication - 8  
Suggested Classification -  
Suggested Technology Center -  
Total Number of Drawing Sheets - 9

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